

# 10N65Z-Q

# 10A, 650V N-CHANNEL POWER MOSFET

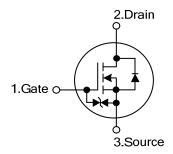
### DESCRIPTION

The **UTC 10N65Z-Q** is a high voltage and high current power MOSFET, designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and a high rugged avalanche characteristics. This power MOSFET is usually used at high speed switching applications in power supplies, PWM motor controls, high efficient DC to DC converters and bridge circuits.

## FEATURES

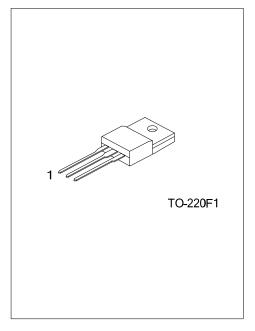
- \*  $R_{DS(ON)}$  =0.950@ V<sub>GS</sub>=10V, I<sub>D</sub>=4.75A
- \* Low gate charge (typical 44 nC)
- \* Low Crss ( typical 18 pF)
- \* Fast switching
- \* 100% avalanche tested
- \* Improved dv/dt capability

### SYMBOL



### ORDERING INFORMATION

Ordering Number		Daakaga	Pin Assignment			Dooking	
Lead Free	Halogen Free	Package	1	2	3	Packing	
10N65ZL-TF1-T	10N65ZG-TF1-T	TO-220F1	G	D	S	Tube	
Note: Pin Assignment: G: Gate D: Drain S: Source							
10N65ZL-TF1-T (1)Packing Type (2)Package Type		<ul> <li>(1) T: Tube</li> <li>(2) TF1: TO-220F1</li> <li>(3) L: Lead Free, G: Halogen Free</li> </ul>					



**Power MOSFET** 

## ■ ABSOLUTE MAXIMUM RATINGS (T<sub>c</sub> = 25°C unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V <sub>DSS</sub>	650	V
Gate-Source Voltage		V <sub>GSS</sub>	± 20	V
Avalanche Current (Note 2)		I <sub>AR</sub>	10	А
Drain Current	Continuous	I <sub>D</sub>	10	А
	Pulsed (Note 2)	I <sub>DM</sub>	38	А
Avalanche Energy	Single Pulsed (Note 3)	E <sub>AS</sub>	250	mJ
	Repetitive (Note 2)	E <sub>AR</sub>	15.6	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	4.5	V/ns
Power Dissipation		PD	50	W
Junction Temperature		TJ	+150	°C
Operating Temperature		T <sub>OPR</sub>	-55 ~ +150	°C
Storage Temperature		T <sub>STG</sub>	-55 ~ +150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature

3. L = 14.2mH,  $I_{AS}$  = 5.93A,  $V_{DD}$  = 50V,  $R_G$  = 25  $\Omega$  Starting  $T_J$  = 25°C

4.  $I_{SD} \le 9.5A$ , di/dt  $\le 200A/\mu s$ ,  $V_{DD} \le BV_{DSS}$ , Starting  $T_J = 25^{\circ}C$ 

### THERMAL DATA

PARAMETER	SYMBOL	RATING	UNIT	
Junction to Ambient	θ <sub>JA</sub> 62.5		°C/W	
Junction to Case	θ <sub>JC</sub>	2.5	°C/W	



#### ■ ELECTRICAL CHARACTERISTICS(T<sub>c</sub>=25°C, unless otherwise specified)

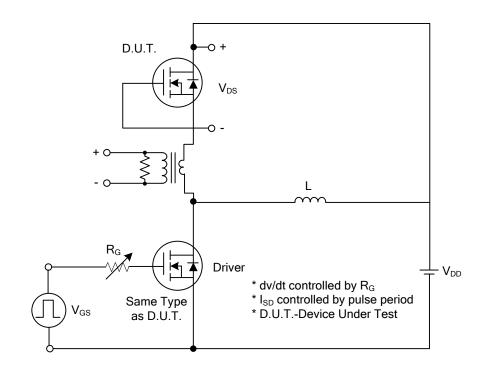
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PARAMETER	SYMBOL	TEST CONDITIONS		MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> = 250µA		650			V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =650V, V <sub>GS</sub> =0V				1	μA
Cata Sauraa Laakaga Currant	I <sub>GSS</sub>	Forward	V <sub>GS</sub> =20V, V <sub>DS</sub> =0V			5	μA
Gate-Source Leakage Current		Reverse	V <sub>GS</sub> =-20V, V <sub>DS</sub> =0V			-5	μA
Breakdown Voltage Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_{J}$	I <sub>D</sub> =250 μΑ	A, Referenced to 25°C		0.7		V/°C
ON CHARACTERISTICS				_			
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,	I <sub>D</sub> =250μΑ	2.0		4.0	V
Static Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =4.75A			0.86	0.95	Ω
DYNAMIC CHARACTERISTICS							
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0 MHz			1300	2040	pF
Output Capacitance	C <sub>OSS</sub>				123	215	pF
Reverse Transfer Capacitance	C <sub>RSS</sub>				15	24	pF
SWITCHING CHARACTERISTICS							
Turn-On Delay Time	t <sub>D(ON)</sub>	V <sub>DD</sub> =325V, I <sub>D</sub> =10A, R <sub>G</sub> =25Ω (Note1, 2)			55	70	ns
Turn-On Rise Time	t <sub>R</sub>				65	150	ns
Turn-Off Delay Time	t <sub>D(OFF)</sub>				300	350	ns
Turn-Off Fall Time	t <sub>F</sub>				95	165	ns
Total Gate Charge	$Q_{G}$	V <sub>DS</sub> =520V, I <sub>D</sub> =10A, V <sub>GS</sub> =10V (Note1, 2)			81	95	nC
Gate-Source Charge	$Q_{GS}$				25		nC
Gate-Drain Charge	$Q_{GD}$				28		nC
DRAIN-SOURCE DIODE CHARACTERIST	ICS AND MA	XIMUM R/	TINGS				
Drain-Source Diode Forward Voltage	$V_{SD}$	V <sub>GS</sub> =0V, I	₅=10A			1.4	V
Maximum Continuous Drain-Source Diode	1	Is				10	^
Forward Current	IS					10	A
Maximum Pulsed Drain-Source Diode Forward Current	I <sub>SM</sub>					38	А
Reverse Recovery Time	t <sub>rr</sub>				420		ns
Reverse Recovery Charge		V <sub>GS</sub> =0V, I <sub>S</sub> =10A, dI <sub>F</sub> /dt=100A/µs (Note1)			420		μC
				- 1	7.4	1	μυ

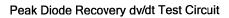
Notes: 1. Pulse Test : Pulse width ≤300µs, Duty cycle ≤2%

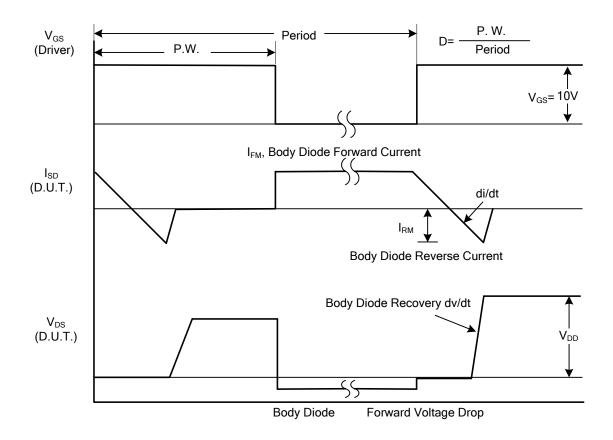
2. Essentially independent of operating temperature



# TEST CIRCUITS AND WAVEFORMS





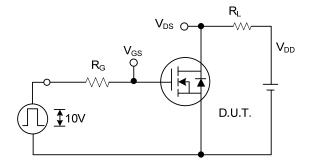


Peak Diode Recovery dv/dt Waveforms

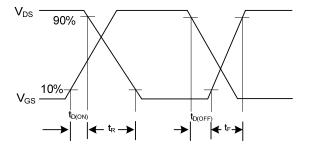


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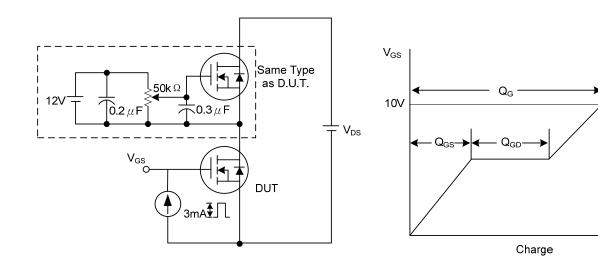
# ■ TEST CIRCUITS AND WAVEFORMS (Cont.)



**Switching Test Circuit** 

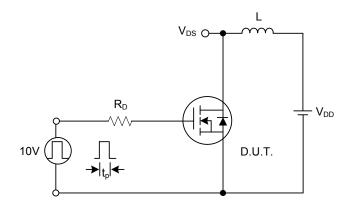


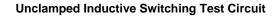
Switching Waveforms

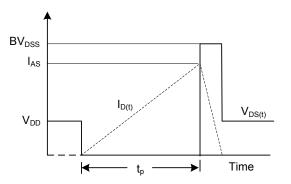


**Gate Charge Test Circuit** 

**Gate Charge Waveform** 







**Unclamped Inductive Switching Waveforms** 



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